



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: [info@chipsmall.com](mailto:info@chipsmall.com) Web: [www.chipsmall.com](http://www.chipsmall.com)

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China




**DXTP560BP5**
**500V PNP SILICON PLANAR HIGH VOLTAGE TRANSISTOR  
POWERDI®5**
**Features and Benefits**

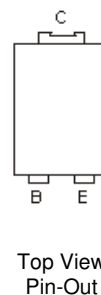
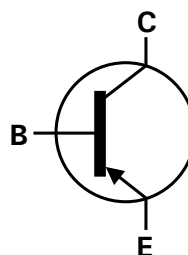
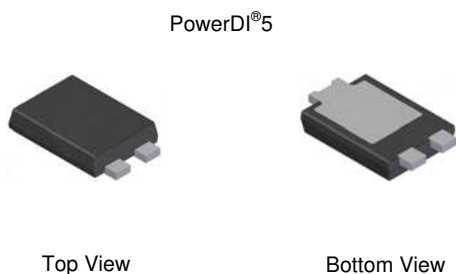
- $BV_{CEO} > -500V$
- $I_C = -150mA$  Continuous Collector Current
- 47% smaller than SOT223; 60% smaller than TO252 (D-PAK)
- Profile height just 1.1mm for thin application
- $R_{\theta JA}$  efficient giving high  $P_D$  rating up to 2.8W
- **"Lead Free", RoHS Compliant (Note 1)**
- **Halogen and Antimony Free, "Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

- Case: POWERDI®5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.093 grams (approximate)

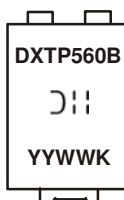
**Applications**

- Gate driver
- Startup switch in offline lighting
- Motor Control


**Ordering Information (Note 3)**

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DXTP560BP5-13	DXTP560B	13	16	5,000

- Notes:
1. No purposefully added lead.
  2. Diodes Inc's "Green" Policy can be found on our website at <http://www.diodes.com>.
  3. For packaging details, go to our website at <http://www.diodes.com>

**Marking Information**


DXTP560B = Product Type Marking Code  
DII = Manufacturers' Code Marking  
K = Factory Designator  
YYWW = Date Code Marking  
YY = Last Two Digits of Year (ex: 10 for 2010)  
WW = Week code (01 - 53)

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

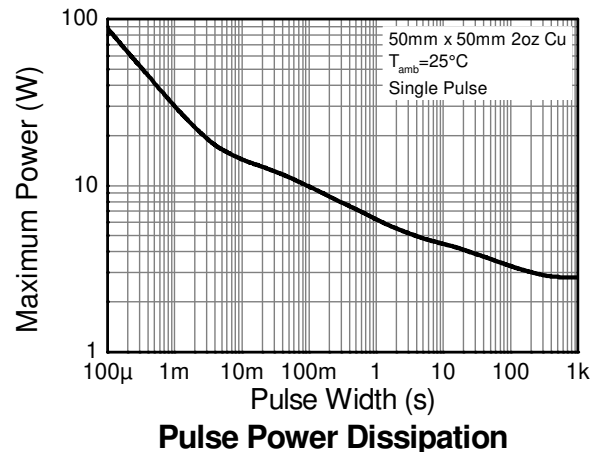
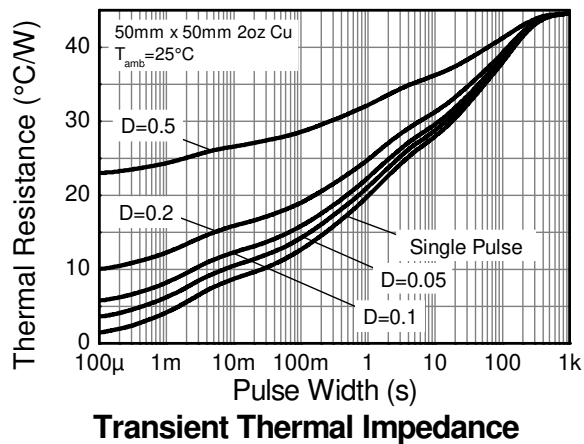
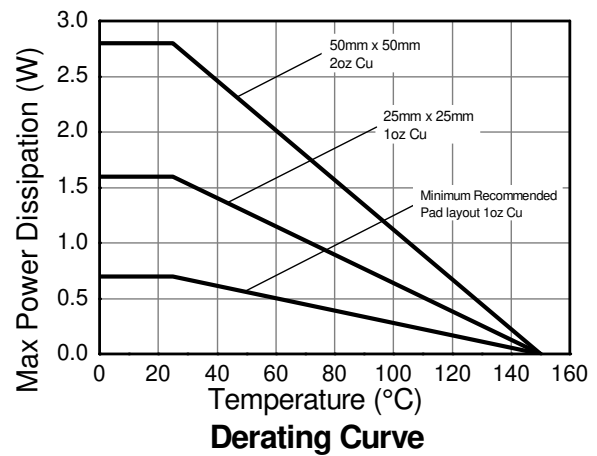
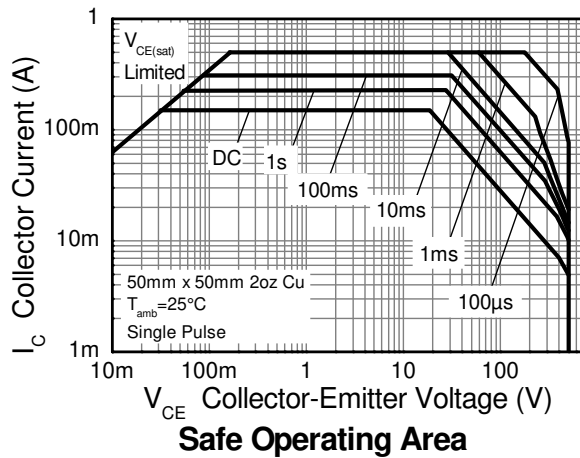
Characteristic		Symbol	Limit	Unit
Collector-Base Voltage		V <sub>CBO</sub>	-500	V
Collector-Emitter Voltage		V <sub>CEO</sub>	-500	
Emitter-Base Voltage		V <sub>EBO</sub>	-7	
Continuous Collector Current	(Note 4)	I <sub>C</sub>	-150	mA
Peak Pulse Current		I <sub>CM</sub>	-500	

**Thermal Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Note 4)	P <sub>D</sub>	2.8	W mW/°C
	(Note 5)		22.4	
	(Note 6)		1.3	
	(Note 7)		10.4	
Thermal Resistance, Junction to Ambient	(Note 4)	R <sub>θJA</sub>	0.7	°C/W
	(Note 5)		5.6	
	(Note 6)		45	
Thermal Resistance, Junction to Lead	(Note 7)	R <sub>θJL</sub>	96	°C/W
	(Note 7)		179	
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

- Notes:
4. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The entire exposed collector pad is attached to the heatsink.
  5. Same as note (4), except the device is mounted on 25mm x 25mm 1oz copper.
  6. Same as note (4), except the device is mounted on a minimum recommended pad layout of 1oz copper.
  7. Thermal resistance from junction to solder-point (at the end of the collector lead).

## Thermal Characteristics



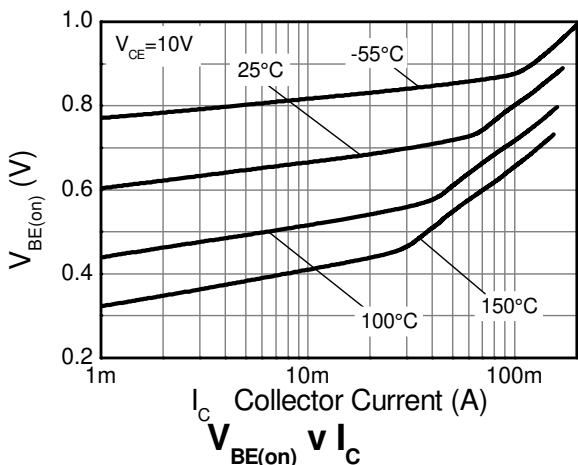
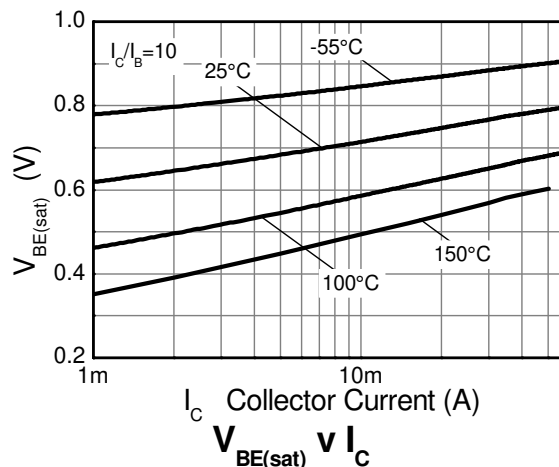
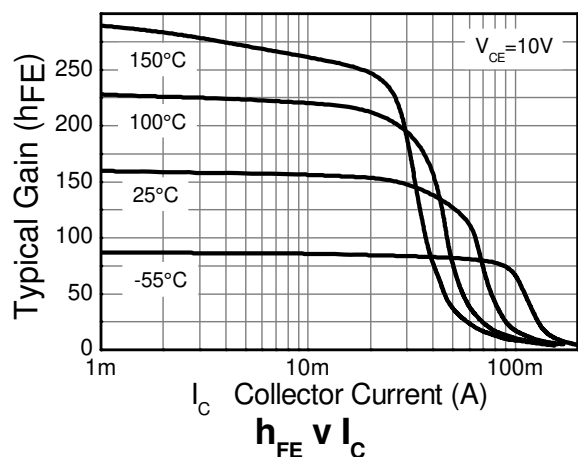
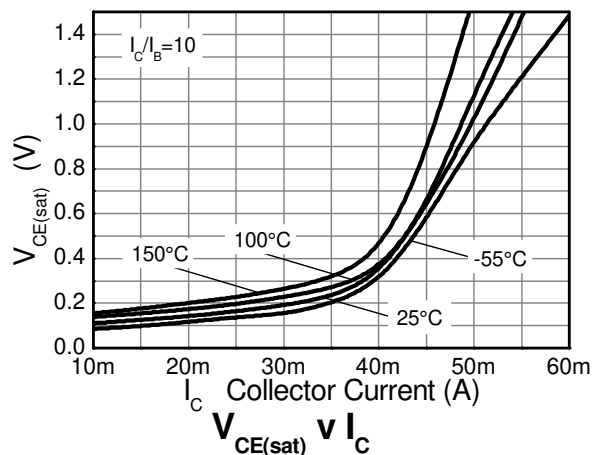
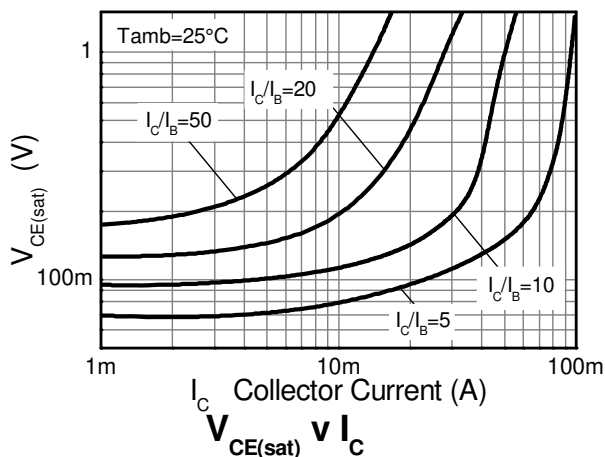


**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-500	—	—	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV <sub>CEO</sub>	-500	—	—	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	—	—	V	I <sub>E</sub> = -100μA
Collector Cutoff Current	I <sub>CBO</sub>	—	—	-100	nA	V <sub>CB</sub> = -500V
Collector Cutoff Current	I <sub>CES</sub>	—	—	-100	nA	V <sub>CE</sub> = -500V
Emitter Cutoff Current	I <sub>EBO</sub>	—	—	-100	nA	V <sub>EB</sub> = -5.6V
Collector-Emitter Saturation Voltage (Note 8)	V <sub>CE(sat)</sub>	—	—	-200 -500	mV	I <sub>C</sub> = -20mA, I <sub>B</sub> = -2mA I <sub>C</sub> = -50mA, I <sub>B</sub> = -10mA
Base-Emitter Saturation Voltage (Note 8)	V <sub>BE(sat)</sub>	—	—	-900	mV	I <sub>C</sub> = -50mA, I <sub>B</sub> = -10mA
Base-Emitter Turn-On Voltage (Note 8)	V <sub>BE(on)</sub>	—	—	-900	mV	V <sub>CE</sub> = -10V, I <sub>C</sub> = -50mA
DC Current Gain (Note 8)	h <sub>FE</sub>	100 80 —	— — 15	300 300 —	—	V <sub>CE</sub> = -10V, I <sub>C</sub> = -1mA V <sub>CE</sub> = -10V, I <sub>C</sub> = -50mA V <sub>CE</sub> = -10V, I <sub>C</sub> = -100mA
Transition Frequency	f <sub>T</sub>	60	—	—	MHz	V <sub>CE</sub> = -20V, I <sub>C</sub> = -10mA, f = 50MHz
Output Capacitance	C <sub>obo</sub>	—	—	8	pF	V <sub>CB</sub> = -20V, f = 1MHz
Switching Times	t <sub>on</sub> t <sub>off</sub>	— —	110 1500	— —	ns	V <sub>CC</sub> = -100V, I <sub>C</sub> = -50mA, I <sub>B1</sub> = 5mA, I <sub>B2</sub> = -10mA

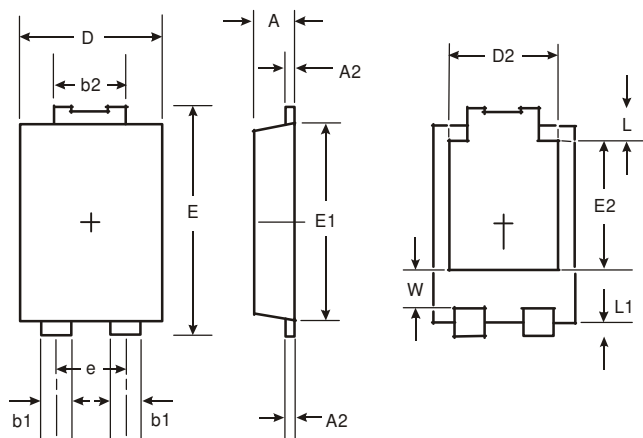
Notes: 8. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

## Typical Electrical Characteristics



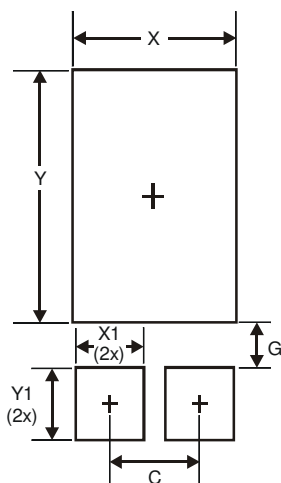
**DXTP560BP5**

## Package Outline Dimensions



POWERDI <sup>®</sup> 5		
Dim	Min	Max
A	1.05	1.15
A2	0.33	0.43
b1	0.80	0.99
b2	1.70	1.88
D	3.90	4.05
D2	3.054 Typ	
E	6.40	6.60
e	1.84 Typ	
E1	5.30	5.45
E2	3.549 Typ	
L	0.75	0.95
L1	0.50	0.65
W	1.10	1.41
All Dimensions in mm		

## Suggested Pad Layout



Dimensions	Value (in mm)
C	1.840
G	0.852
X	3.360
X1	1.390
Y	4.860
Y1	1.400

**IMPORTANT NOTICE**

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

**LIFE SUPPORT**

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or
2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2011, Diodes Incorporated

[www.diodes.com](http://www.diodes.com)